

Universal Highlights Uflex at SMTA International

VISIT UNIVERSAL INSTRUMENTS on BOOTH 223



September 19-20 | Rosemont, IL

Process expertise and applications experience complement versatile equipment portfolio to deliver superior automation solutions

Universal will feature the ultra-flexible **Uflex™** platform, one solution in an extensive automation lineup that addresses virtually every automation challenge, at the SMTA International trade show on **Booth 223**.

Universal will also have experts from its renowned Advanced Process Lab (APL) on the booth to share insights on current and emerging technologies and help visitors optimize their manufacturing operations.

Uflex.



Ultimate flexibility. Simplified automation.

Uflex features a revolutionary architecture that enables user-level programming and field reconfigurability to speed time to market and dramatically shorten the payback period.

[Find out more](#)



Knowledge makes the difference.

The **APL** is a major contributor to the **SMTA Technical Conference** and will be presenting on the following topics on **September 21** in Session LF1 of the **Lead-Free Soldering Symposium** at this year's event:

- Thermal Cycle Reliability Assessment of Bowed PCB Assemblies
- The Effect of Die Size on the Thermal Fatigue Reliability and Failure Mode of a Chip Array BGA
- Effect of Process Thermal History on the Microstructure of Copper Pillar SnAg Solder Joints

[Find out more](#)

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